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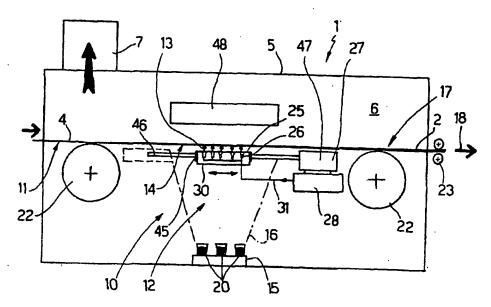
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(54) Title: A METHOD AND APPARATUS FOR DEPOSITION OF FILMS OF COATING MATERIALS, IN PARTICULAR OF SUPERCONDUCTIVE OXIDES



(57) Abstract: There are provided herein a method and an apparatus for deposition of films of coating materials on a substrate, of particular use in obtaining superconductive composite tapes for deposition of films of superconductive oxides and/or buffer layers. A step of deposition of the film (2) on the substrate (4) is associated to a step of gas treatment in situ, in which a flow (13) of gas is sent towards a working surface (14) of the substrate or of the film growing on the substrate. The gas-treatment step is performed via ultrasoundexpansion nozzles (26).

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